

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|--|--------------------|------------------|
| 1 | 261 | (thinning with (substrate wafer)) and ("grid" "waffle") | USPAT; US-PGPUB | 2003/07/22 10:10 |
| 2 | 2624 | (thinning with (substrate wafer)) | USPAT; US-PGPUB | 2003/07/22 10:10 |
| 3 | 22264 | metal with mask | USPAT; US-PGPUB | 2003/07/22 10:11 |
| 4 | 14 | ((thinning with (substrate wafer))) with (metal with mask) | USPAT; US-PGPUB | 2003/07/22 10:11 |
| - | 1752 | ((43/460) or (438/463) or (438/606) or (438/107) or (438/620) or (438/712) or (438/718) or (438/728) or (438/733) or (738/742)).CCLS. | USPAT; US-PGPUB | 2003/07/21 08:55 |
| - | 11 | ((43/460) or (438/463) or (438/606) or (438/107) or (438/620) or (438/712) or (438/718) or (438/728) or (438/733) or (738/742)).CCLS.) and (thinning with (substrate wafer)) and ("grid" "waffle") | USPAT; US-PGPUB | 2003/07/21 09:50 |
| - | 260 | (thinning with (substrate wafer)) and ("grid" "waffle") | USPAT; US-PGPUB | 2003/07/22 10:09 |
| - | 11 | ("5096854" "5213657" "5840614" "5891298" "5968849" "5981391" "6017822" "6020252" "6033995" "6046117" "6100166").PN. | USPAT | 2003/07/21 09:48 |
| - | 0 | 6162702.URPN. | USPAT | 2003/07/21 09:49 |
| - | 2618 | (thinning with (substrate wafer)) | USPAT; US-PGPUB | 2003/07/21 09:51 |
| - | 15144 | radio with frequency with circuit | USPAT; US-PGPUB | 2003/07/21 09:51 |
| - | 0 | ((thinning with (substrate wafer))) with (radio with frequency with circuit) | USPAT; US-PGPUB | 2003/07/21 09:52 |
| - | 27 | ((thinning with (substrate wafer))) and (radio with frequency with circuit) | USPAT; US-PGPUB | 2003/07/21 09:52 |
| - | 7 | 5336930.URPN. | USPAT | 2003/07/21 10:02 |
| - | 13 | 5221221.URPN. | USPAT | 2003/07/21 10:19 |
| - | 7 | 5336930.URPN. | USPAT | 2003/07/21 10:20 |
| - | 9 | ("3648131" "4447291" "4507674" "4789645" "4849376" "4965218" "4970578" "4972250" "4977100").PN. | USPAT | 2003/07/21 10:21 |
| - | 10 | 4970578.URPN. | USPAT | 2003/07/21 10:22 |
| - | 10 | 4970578.URPN. | USPAT | 2003/07/21 10:29 |
| - | 14 | ("3986196" "4091408" "4374394" "4376287" "4571611" "4601096" "4751562" "4794093" "4807022" "4818724" "4823174" "4827610" "4868613" "4896194").PN. | USPAT | 2003/07/21 10:30 |
| - | 12 | 4868613.URPN. | USPAT | 2003/07/21 10:32 |
| - | 12 | 5064772.URPN. | USPAT | 2003/07/21 10:35 |
| - | 0 | mmic with thinning with (substrate wafer) | USPAT; US-PGPUB | 2003/07/21 10:35 |
| - | 0 | mmic and (thining with (substrate wafer)) | USPAT; US-PGPUB | 2003/07/21 10:36 |
| - | 7 | (thining with (substrate wafer)) | USPAT; US-PGPUB | 2003/07/21 10:37 |
| - | 2618 | (thinning with (substrate wafer)) | USPAT; US-PGPUB | 2003/07/22 10:10 |
| - | 29 | ((thinning with (substrate wafer))) and mmic | USPAT; US-PGPUB | 2003/07/21 10:38 |
| - | 0 | 10034723.pn. | USPAT; US-PGPUB | 2003/07/21 11:38 |
| - | 0 | "10034723" | USPAT; US-PGPUB | 2003/07/21 11:41 |
| - | 0 | ((thinning with (substrate wafer))) and vernier with marker | USPAT; US-PGPUB | 2003/07/21 11:41 |
| - | 48 | vernier with marker | USPAT; US-PGPUB | 2003/07/21 11:48 |
| - | 438 | 438/462.ccls. | USPAT; US-PGPUB | 2003/07/21 11:49 |
| - | 41 | 438/462.ccls. and thinning with (substrate wafer) | USPAT; US-PGPUB | 2003/07/21 11:51 |

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| - | 0 | 438/462.ccls. and mmisc | USPAT; US-PGPUB | 2003/07/21 11:51 |
| - | 7 | 438/462.ccls. and mmic | USPAT; US-PGPUB | 2003/07/21 11:52 |
| - | 29 | 438/462.ccls. and depth with mark | USPAT; US-PGPUB | 2003/07/21 12:03 |
| - | 2 | 438/462.ccls. and backside and (depth with mark) | USPAT; US-PGPUB | 2003/07/21 12:04 |
| - | 12 | 438/462.ccls. and backside and ((alignment depth) with mark) | USPAT; US-PGPUB | 2003/07/21 13:03 |
| - | 0 | "09034747" | USPAT; US-PGPUB | 2003/07/21 13:05 |
| - | 0 | "10034747" | USPAT; US-PGPUB | 2003/07/21 13:05 |
| - | 2 | measured with via with etch with etching | USPAT; US-PGPUB | 2003/07/21 13:05 |
| - | 0 | (measured with via with hole with etching) and bernier | USPAT; US-PGPUB | 2003/07/21 13:06 |
| - | 0 | (measured with via with hole with etching) and vernier | USPAT; US-PGPUB | 2003/07/21 13:06 |
| - | 6 | measured with via with hole with etching | USPAT; US-PGPUB | 2003/07/21 13:06 |
| - | 1945 | hemt | USPAT; US-PGPUB | 2003/07/22 08:50 |
| - | 382 | hemt and mmic | USPAT; US-PGPUB | 2003/07/22 08:50 |
| - | 117 | (hemt and mmic) and pad | USPAT; US-PGPUB | 2003/07/22 08:50 |
| - | 0 | ((hemt and mmic) and pad) and thinning with (substrate wafer) | USPAT; US-PGPUB | 2003/07/22 08:57 |
| - | 37 | ((hemt and mmic) and pad) and (thin thins thinning) with (substrate wafer) | USPAT; US-PGPUB | 2003/07/22 08:59 |
| - | 87 | (hemt and mmic) and mmic and ((source and drain) with region) | USPAT; US-PGPUB | 2003/07/22 09:01 |
| - | 21 | ((hemt and mmic) and mmic and ((source and drain) with region)) and ((source and drain) with pad) | USPAT; US-PGPUB | 2003/07/22 09:01 |